查询"2SK343和 Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK3438

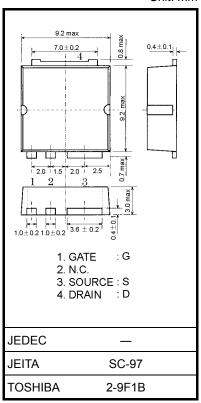
DC-DC Converter, Relay Drive and Motor Drive Applications

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- Low drain-source ON resistance: RDS (ON) =  $0.74 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 4.5 \text{ S} (typ.)$
- Low leakage current:  $I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 600 \ V)$
- Enhancement mode:  $V_{th} = 3.0 \sim 5.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

#### Absolute Maximum Ratings (Ta = 25°C)

| Characteristics                                      |                   | Symbol           | Rating  | Unit |  |
|--|-------------------|------------------|---------|------|--|
| Drain-source voltage                                 |                   | V <sub>DSS</sub> | 600     | V    |  |
| Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ ) |                   | V <sub>DGR</sub> | 600     | V    |  |
| Gate-source voltage                                  |                   | V <sub>GSS</sub> | ±30     | V    |  |
| Drain current  | DC (Note 1)       | ۱ <sub>D</sub>   | 10      |      |  |
|  | Pulse<br>(Note 1) | I <sub>DP</sub>  | 30      | A    |  |
| Drain power dissipation (Tc = $25^{\circ}$ C)        |                   | PD               | 80      | W    |  |
| Single pulse avalanche energy<br>(Note 2)            |                   | E <sub>AS</sub>  | 252     | mJ   |  |
| Avalanche current                                    |                   | I <sub>AR</sub>  | 10      | А    |  |
| Repetitive avalanche energy (Note 3)                 |                   | E <sub>AR</sub>  | 8       | mJ   |  |
| Channel temperature                                  |                   | T <sub>ch</sub>  | 150     | °C   |  |
| Storage temperature range                            |                   | T <sub>stg</sub> | -55~150 | °C   |  |



Weight: 0.74 a (tvp.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

### **Thermal Characteristics**

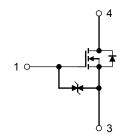
| Characteristics                     | Symbol                 | Max  | Unit |
|-------------------------------------|------------------------|------|------|
| Thermal resistance, channel to case | R <sub>th (ch-c)</sub> | 1.56 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 4.41 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.





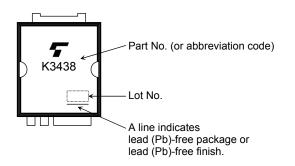
Eterrica PCharacteristics (Ta = 25°C)

| Chara  | acteristics    | Symbol               | Test Condition   | Min | Тур. | Max | Unit |
|--|----------------|----------------------|--|-----|------|-----|------|
| Gate leakage current                               |                | I <sub>GSS</sub>     | $V_{GS}=\pm 25~V,~V_{DS}=0~V$  |     |      | ±10 | μA   |
| Drain-source bre                                   | akdown voltage | V (BR) GSS           | $I_G=\pm 10~\mu A,~V_{DS}=0~V$   | ±30 |      |     | V    |
| Drain cut-OFF cu                                   | ırrent         | I <sub>DSS</sub>     | $V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$   |     |      | 100 | μA   |
| Drain-source bre                                   | akdown voltage | V (BR) DSS           | $I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$  | 600 | _    | _   | V    |
| Gate threshold ve                                  | oltage         | V <sub>th</sub>      | $V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$  | 3.0 | _    | 5.0 | V    |
| Drain-source ON                                    | resistance     | R <sub>DS (ON)</sub> | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$   |     | 0.74 | 1.0 | Ω    |
| Forward transfer                                   | admittance     | Y <sub>fs</sub>      | $V_{DS} = 15 \text{ V}, \text{ I}_{D} = 5 \text{ A}$   | 2.0 | 4.5  |     | S    |
| Input capacitance<br>Reverse transfer capacitance  |                | C <sub>iss</sub>     | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz   |     | 1200 |     | pF   |
|  |                | C <sub>rss</sub>     |  |     | 10   |     |      |
| Output capacitance                                 |                | C <sub>oss</sub>     |  |     | 130  |     |      |
| Switching time                                     | Rise time      | tr                   | $V_{GS}^{10 V} \downarrow I_D = 5 \text{ A } V_{OUT}$ $V_{GS}^{0 V} \downarrow I_D = 60 \Omega$ $K_L = 60 \Omega$ $V_{DD} \simeq 300 V$ $Duty \le 1\%, t_W = 10 \mu s$ |     | 13   |     | ns   |
|  | Turn-ON time   | t <sub>on</sub>      |  |     | 40   |     |      |
|  | Fall time      | t <sub>f</sub>       |  |     | 8    | _   |      |
|  | Turn-OFF time  | t <sub>off</sub>     |  | _   | 50   |     |      |
| Total gate charge<br>(gate-source plus gate-drain) |                | Qg                   |  |     | 28   |     | nC   |
| Gate-source charge                                 |                | Q <sub>gs</sub>      | $V_{DD} \simeq 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$   |     | 16   | —   |      |
| Gate-drain ("miller") charge                       |                | Q <sub>gd</sub>      |  | —   | 12   | —   |      |

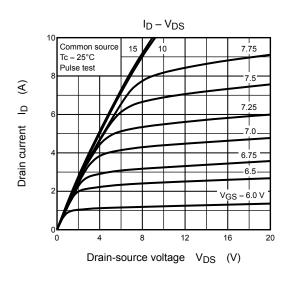
## Source-Drain Ratings and Characteristics (Ta = 25°C)

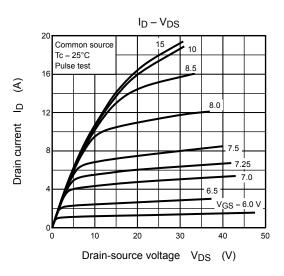
| Characteristics                           | Symbol           | Test Condition                                 | Min | Тур. | Max  | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | —  | _   | _    | 10   | А    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> | —  | _   | _    | 30   | А    |
| Forward voltage (diode)                   | V <sub>DSF</sub> | I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V  | _   | _    | -1.7 | V    |
| Reverse recovery time                     | t <sub>rr</sub>  | I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V, | _   | 1600 | _    | ns   |
| Reverse recovery charge                   | Q <sub>rr</sub>  | dI <sub>DR</sub> /dt = 100 A/μs                | _   | 17   | _    | μC   |

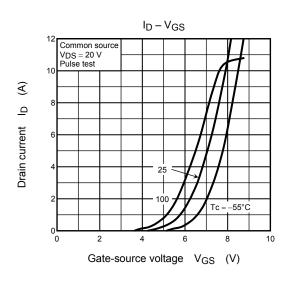
## Marking

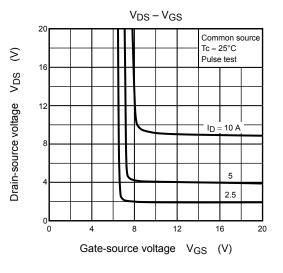


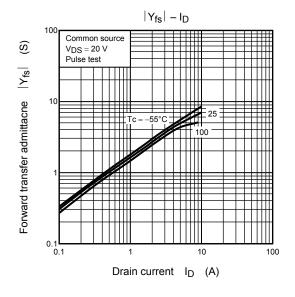
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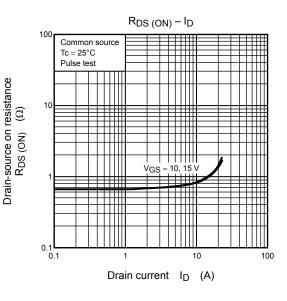




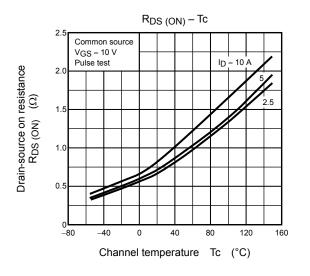


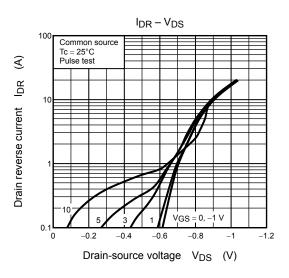


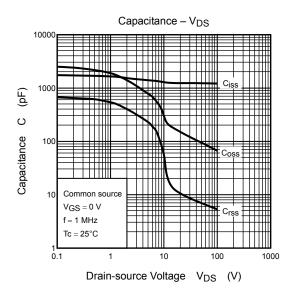


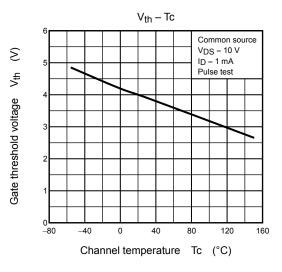


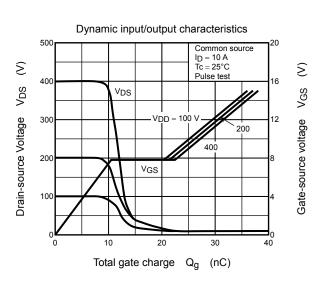
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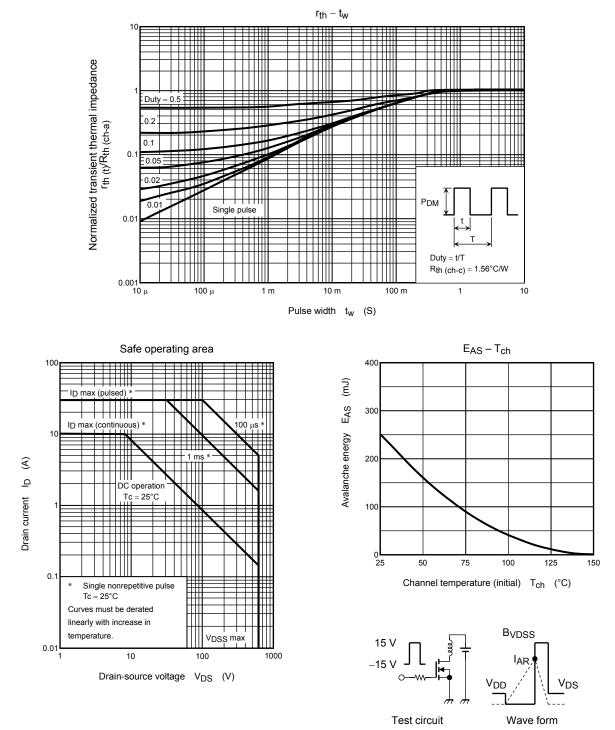






P<sub>D</sub> – Tc 100 Ś 80  $\mathsf{P}_{\mathsf{D}}$ Drain Power dissipation 60 40 20 ٥Ľ 40 80 120 160 200 Channel temperature Tc (°C)

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